



MICRO-FAZE® 3A4

Dry-to-touch Thermal Pad

Product Code: 52061



TECHNICAL DATA SHEET

THERMALLY CONDUCTIVE INTERFACE MATERIAL

Product Description

MICRO-FAZE® 3A4 is a revolutionary new thermal interface film formulated with non-silicone thermal grease. It was developed by AOS to offer the lowest thermal resistance in a thermal interface without the mess of grease. MICRO-FAZE 3A4 is a die-cut aluminum foil substrate coated on both sides with specially formulated thermal grease that is naturally tacky but dry to the touch. MICRO-FAZE 3A4 is non-wax-based and offers unique heat transfer properties.



Product Features & Benefits

- MICRO-FAZE 3A4 retains all the unique advantages of thermal grease but in the form of a thermal interface film.
- Minimum force is required to achieve total interface contact.
- MICRO-FAZE allows for total “wetting action” to fill all microscopic surface voids without changing phase.
- Unlike phase change materials, heat transfer starts at 25°C or lower, making MICRO-FAZE 3A4 an excellent choice for cold plate applications.
- Offers maximum heat transfer capability for power components.
- Excellent replacement for phase change materials and silicone pads.
- MICRO-FAZE 3A4 is a “drop-in-place” product that is easy to use and handle in a manufacturing environment.
- Naturally tacky – no adhesive, fiberglass or other non-conductive material is used that may reduce thermal resistance.
- Microscopically changes to fill all microscopic voids on part surfaces.
- Thixotropic nature prevents run out.

Major Applications

- Power modules, IGBTs, DC-DC converter modules, solid state relays, diodes, power MOSFETs, RF components and thermoelectric modules.
- Microprocessors, multichip modules, ASICs and other digital components.
- Power amplifiers, large area applications for power supplies and other custom enclosure heat dissipating surfaces.

Available Configurations

MICRO-FAZE 3A4 is available in rolls and can be die-cut to exact specifications.

Typical Properties

Physical Properties	3A4
Substrate	Aluminum
Substrate Thickness	0.002in.
Compound Thickness (per side)	0.001in.
Total Thickness	0.004in.
Thermal Properties	
Thermal Resistance @ 50 psi	0.032 °C-in ² / W
Estimated Thermal Conductivity (ASTM D-5470 modified)	4.5 W/m-K

AOS Thermal Compounds, LLC

22 Meridian Road, Suite 6, Eatontown, NJ 07724

Tel 732.389.5514 Fax 732.389.6380 E-mail sales@aosco.com Web www.aosco.com